

Supplementary Information

Effective Interfacial Energy Band Engineering Strategy toward High-performance Triboelectric Nanogenerator

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Supplementary Note S1

Energy band calculation formula

$$W_F = 21.22 \text{ eV} - E_{\text{cut-off}}$$

$$E_F = 0 - W_F$$

$$E_V = E_F - E_{\text{onset}}$$

$$E_C = E_V + E_g$$

Supplementary Note S2

To calculate the relative permittivity of ZrO_x , $La_{0.1}Zr_{0.9}O_x$, and $La_{0.2}Zr_{0.8}O_x$ HPEBL, the equation can be expressed by:

$$\varepsilon_r = \frac{C_{area} \cdot d}{\varepsilon_0}$$

Where the measured average area capacitance C_{area} of ZrO_x , $La_{0.1}Zr_{0.9}O_x$, and $La_{0.2}Zr_{0.8}O_x$ HPEBL shown in Figure 4c are 488.4 nF cm^{-2} , 355.1 nF cm^{-2} , and 333.5 nF cm^{-2} . The thicknesses of the ZrO_x , $La_{0.1}Zr_{0.9}O_x$, and $La_{0.2}Zr_{0.8}O_x$ HPEBL are 35nm, 55 nm, and 60 nm. The diameter of the MIM unit shown in the red frame of Figure 4a is 0.3 mm, thus the area size is $2.83 \times 10^{-7} \text{ m}^2$.

Therefore, the calculated results of relative permittivity of ZrO_x , $La_{0.1}Zr_{0.9}O_x$, and $La_{0.2}Zr_{0.8}O_x$ HPEBL can be listed in the following table:

	ZrO_x	$La_{0.1}Zr_{0.9}O_x$	$La_{0.2}Zr_{0.8}O_x$
ε_r	19.3	22	22.6

Supplementary Note S3

We constructed the intermediate layer based TENG shown in following figure to derive the relationship between maximum surface charge density (σ_m) and the thickness of the intermediate layer (d_2). According to Gauss's law:

$$E_1 = \frac{-\sigma_x}{\varepsilon_0 \varepsilon_{r1}} \quad (1)$$

$$E_2 = \frac{-\sigma_x}{\varepsilon_0 \varepsilon_{r2}} \quad (2)$$

$$E_{air} = \frac{-\sigma_x + \sigma_0}{\varepsilon_0} \quad (3)$$

And the total potential difference could be expressed as:

$$\Delta V_E = E_{air}x + E_1 d_1 + E_2 d_2 = -\frac{\sigma_x}{\varepsilon_0} \left(\frac{d_1}{\varepsilon_{r1}} + \frac{d_2}{\varepsilon_{r2}} + x \right) + \frac{\sigma_0 x}{\varepsilon_0} \quad (4)$$

$$\text{Let } d_0 = \frac{d_1}{\varepsilon_{r1}} + \frac{d_2}{\varepsilon_{r2}}$$

At short-circuit, let $\Delta V_E = 0$

$$\text{Then we obtain } \sigma_x = \frac{\sigma_0 x}{\frac{d_1}{\varepsilon_{r1}} + \frac{d_2}{\varepsilon_{r2}} + x} = \frac{\sigma_0 x}{d_0 + x}$$

According to the capacitor model:

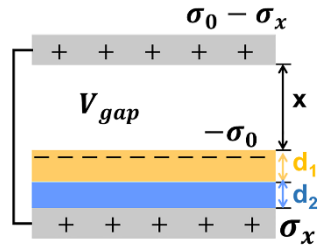
$$V_{gap} = \frac{\sigma_0 d_0 x}{\varepsilon_0 (d_0 + x)} \quad (5)$$

Considering the limitation of Paschen's law:

$$V = \frac{BPx}{\ln(Px) + C} \quad (6)$$

And we let $V_{gap} = V$ to get the maximum surface charge density σ_m :

$$\sigma_m = \left(\frac{BP\varepsilon_0(d_0+x)}{(\ln(Px)+C)d_0} \right)_{min} = \left(\frac{BP\varepsilon_0 \left(1 + \frac{x}{d_0}\right)}{(\ln(Px)+C)} \right)_{min} \quad (7)$$



Charge distribution model of intermediate layer based TENG

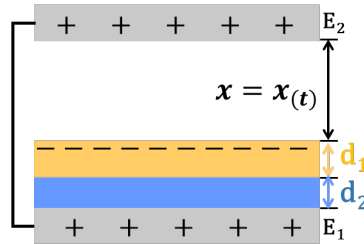
According to the above expression of σ_m , the maximum surface charge density increases as the effective thickness decreases. In this case, only the influence of thickness variable is considered, and the impact of possible polarization field or polarizability is neglected.

Supplementary Note S4

Calculation on output power and energy conversion efficiency

The following table shows parameters of the $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ HPEBL based TENG:

Parameter	Value
Mass of the device without Al: m_d	0.3936 g
Mass of the whole device: m_{TENG}	0.4112 g
Volume of the whole device: V_{TENG}	0.16 cm^3
Maximum separation distance: x_{max}	4 mm
Operation frequency: f	2 Hz
Thickness of PDMS: d_1	10 μm
Thickness of intermediate layer $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$: d_2	0.05 μm
Relative permittivity of PDMS: ϵ_{r1}	2.64
Relative permittivity of $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$: ϵ_{r2}	22
Effective thickness of the dielectric layer: $d_0 = d_1/\epsilon_{r1} + d_2/\epsilon_{r2}$	3.79 μm
Surface charge: Q	97.3 nC
Contact surface area: S	4 cm^2
Maximized output energy per cycle: $E_{\text{per cycle}}$	12.2 μJ



Model of the $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ HPEBL based TENG

$$P_{\text{mass}} = \frac{E_{\text{per cycle}}}{t_{\text{per cycle}} \cdot m} = \frac{12.2 \mu\text{J}}{0.5 \text{ s} \times 0.4112 \text{ g}} = 59.34 \mu\text{W/g}$$

$$P_{\text{volume}} = \frac{E_{\text{per cycle}}}{t_{\text{per cycle}} \cdot V} = \frac{12.2 \mu\text{J}}{0.5 \text{ s} \times 0.16 \text{ cm}^3} = 152.5 \mu\text{W/cm}^3$$

$$Q_{E_1} = Q_{SC(t)} = \frac{S\sigma x(t)}{d_0 + x(t)} = \frac{Qx(t)}{d_0 + x(t)}$$

$$Q_{dielectric} = -Q$$

$$Q_{fixed} = Q_{E_1} + Q_{dielectric} = \frac{Qx(t)}{d_0 + x(t)} - Q = -\frac{Qd_0}{d_0 + x(t)}$$

$$\text{From Gauss theorem: } E_{fixed} = \frac{|Q_{fixed}|}{2S\epsilon_0} = \frac{Qd_0}{2S\epsilon_0[d_0 + x(t)]}$$

$$Q_{E_2} = -Q_{fixed} = \frac{Qd_0}{d_0 + x(t)}$$

$$\begin{aligned} W_{electrostatic\ force} &= F \cdot x(t) = E_{fixed} \cdot Q_{E_2} \cdot x(t) \\ &= \frac{Qd_0}{2S\epsilon_0[d_0 + x(t)]} \cdot \frac{Qd_0}{d_0 + x(t)} \cdot x(t) = \frac{(Qd_0)^2 x(t)}{2S\epsilon_0[d_0 + x(t)]^2} \end{aligned}$$

Energy due to electrostatic force of half cycle:

$$W_{electrostatic\ force} = \int_0^{x_{max}} \frac{(Qd_0)^2 x(t)}{2S\epsilon_0[d_0 + x(t)]^2} dx$$

Gravimetric Power Density	Volumetric Power Density	Energy Conversion Efficiency
59.34 $\mu W/g$	152.5 $\mu W/cm^3$	39.2%

Therefore, the total input energy of half cycle:

$$E_{input} = mgx_{max} + W_{electrostatic\ force}$$

$$= 1.542912 \times 10^{-5} J + 1.145454 \times 10^{-10} J = 15.5436654 \mu J$$

$$E_{output} = E_{per\ cycle}/2 = 6.1 \mu J$$

$$\eta = E_{output}/E_{input} \times 100\% = 6.1 \mu J / 15.5436654 \mu J \times 100\% = 39.2\%$$

The summarized gravimetric power density, volumetric power density and energy conversion efficiency of the $La_{0.1}Zr_{0.9}O_x$ HPEBL based TENG are listed in the following table.

Supplementary Note S5

The interfacial electric field applied between to the HPEBL can be calculated with the following equation:

$$E = \frac{Q}{S\epsilon_0\epsilon_r}$$

Where the maximized charge density could be smaller than the transfer charge density $Q/S=243.3 \mu\text{C m}^{-2}$. Therefore, for intermediate layers with different relative permittivity, the calculated maximum interfacial electric field can be presented as 0.0142 MV/cm, 0.0125 MV/cm and 0.0122 MV/cm with ZrO_x , $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$, and $\text{La}_{0.2}\text{Zr}_{0.8}\text{O}_x$ layer. Combined with the measured leakage current shown in Figure 4d, the leakage current outputs are $5.68 \times 10^{-5} \text{ A/m}^2$, $3.07 \times 10^{-5} \text{ A/m}^2$ and $1.02 \times 10^{-4} \text{ A/m}^2$ respectively. The $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ film possess the best anti-leakage performance.

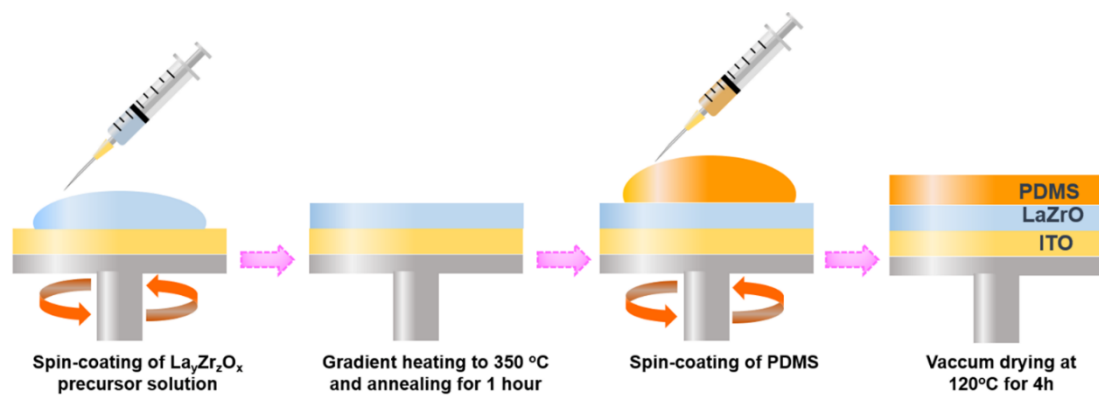


Fig. S1 Fabrication process of the LaZrO HPEBL based TENG.

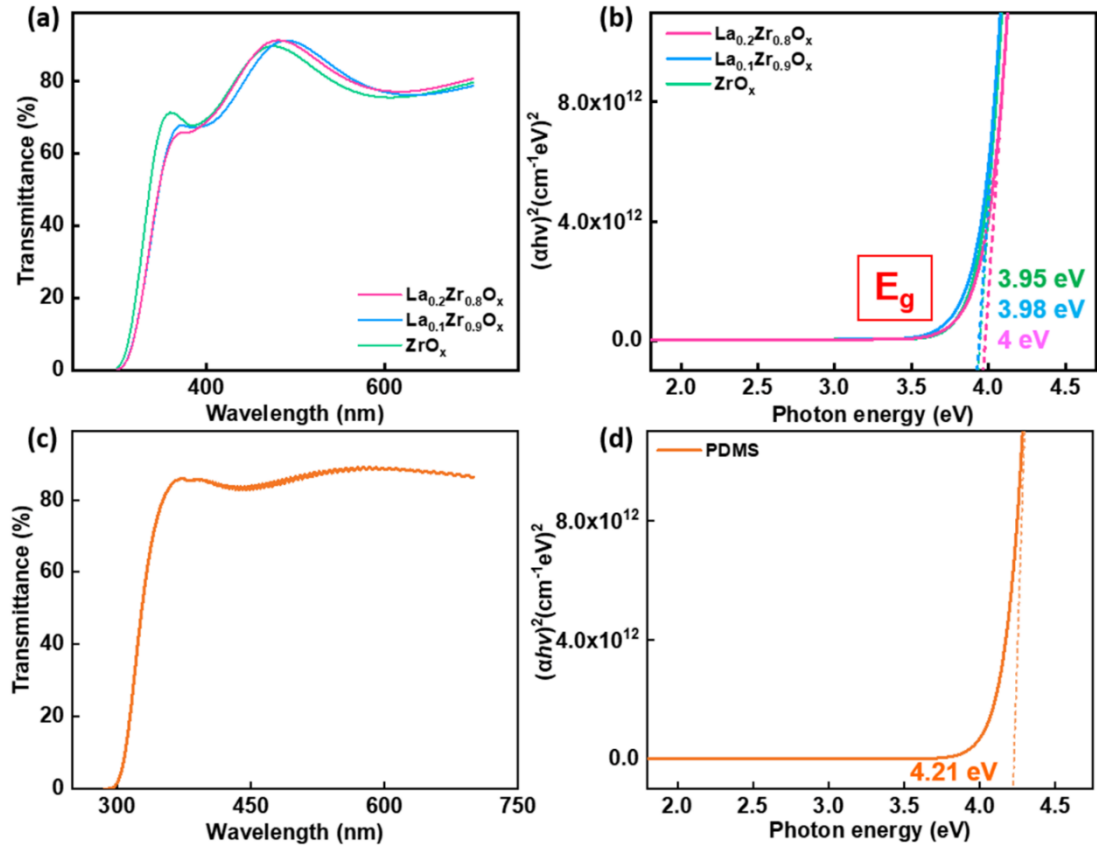


Fig. S2 (a) Transmittance spectra and (b) Evaluation of the $(ah\nu)^2$ versus $h\nu$ curves of various LaZrO films with a role of La content varying from 0 to 20%. (c) Transmittance spectra and (d) Evaluation of the $(ah\nu)^2$ versus $h\nu$ curves of PDMS.

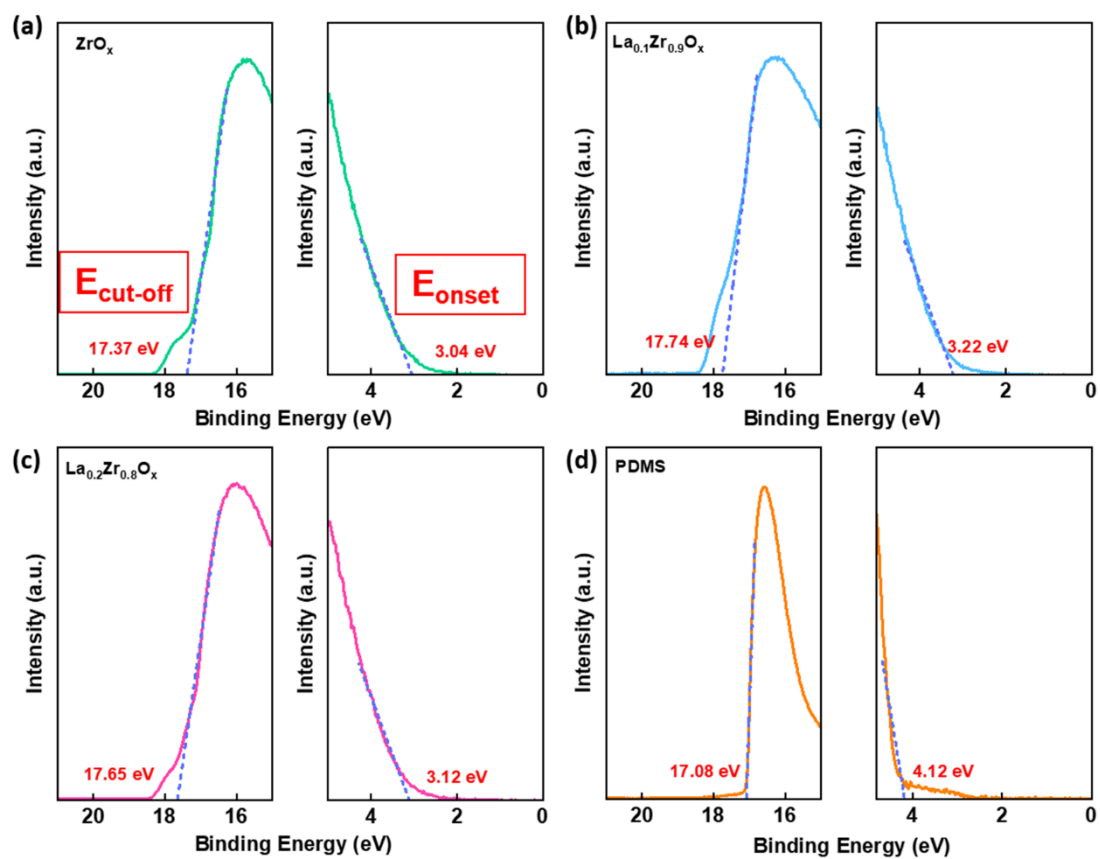


Fig. S3 Ultraviolet Photoelectron Spectrometer (UPS) pattern of (a) ZrO_x , (b) $La_{0.1}Zr_{0.9}O_x$, (c) $La_{0.2}Zr_{0.8}O_x$, and (d) PDMS respectively.

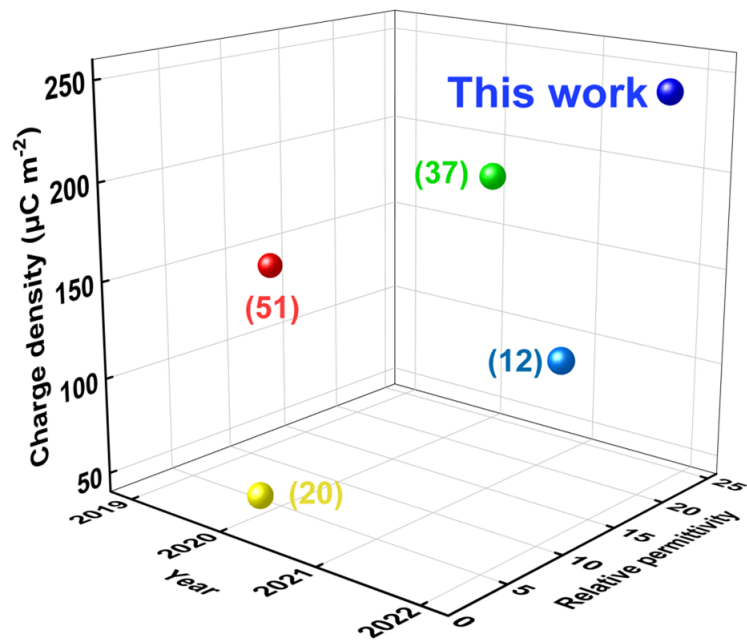


Fig. S4 Comparison to recent works about relative permittivity and transferred charge density.

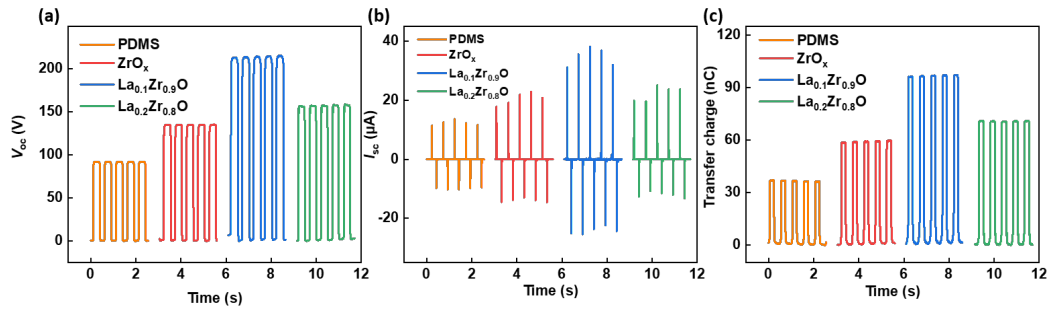


Fig. S5 (a) Open-circuit voltage, (b) Short-circuit current and (c) Transferred charge density of different TENG devices without LaZrO, with ZrO_x , $La_{0.1}Zr_{0.9}O_x$, and $La_{0.2}Zr_{0.8}O_x$, respectively.

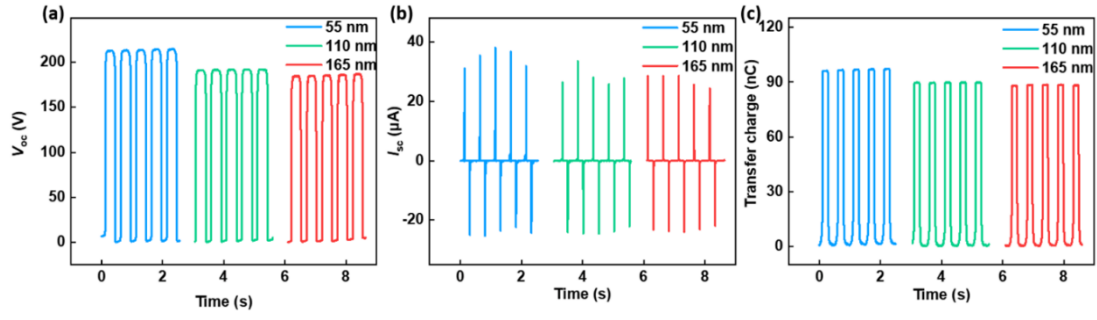


Fig. S6 (a) Open-circuit voltage, (b) Short-circuit current and (c) Transferred charge density of different TENG devices with different thicknesses of $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$.

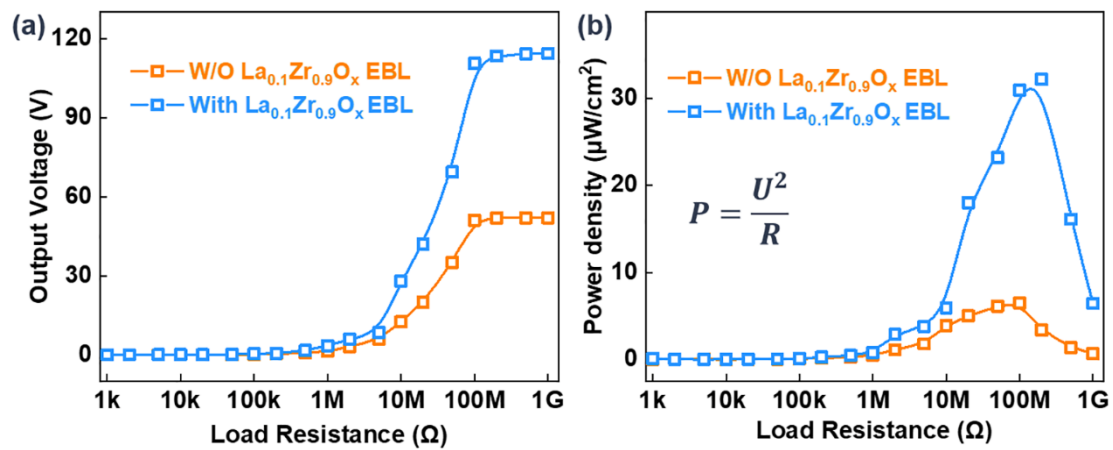


Fig. S7 Variation of voltage and peak power density as a function of load resistance.

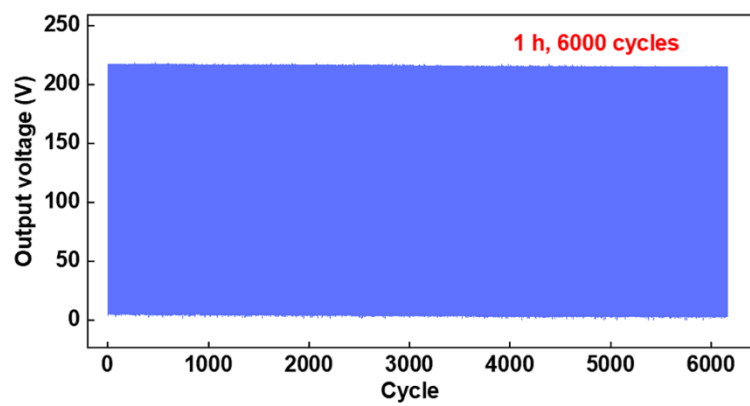


Fig. S8 Stability of $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ HPEBL based TENG.

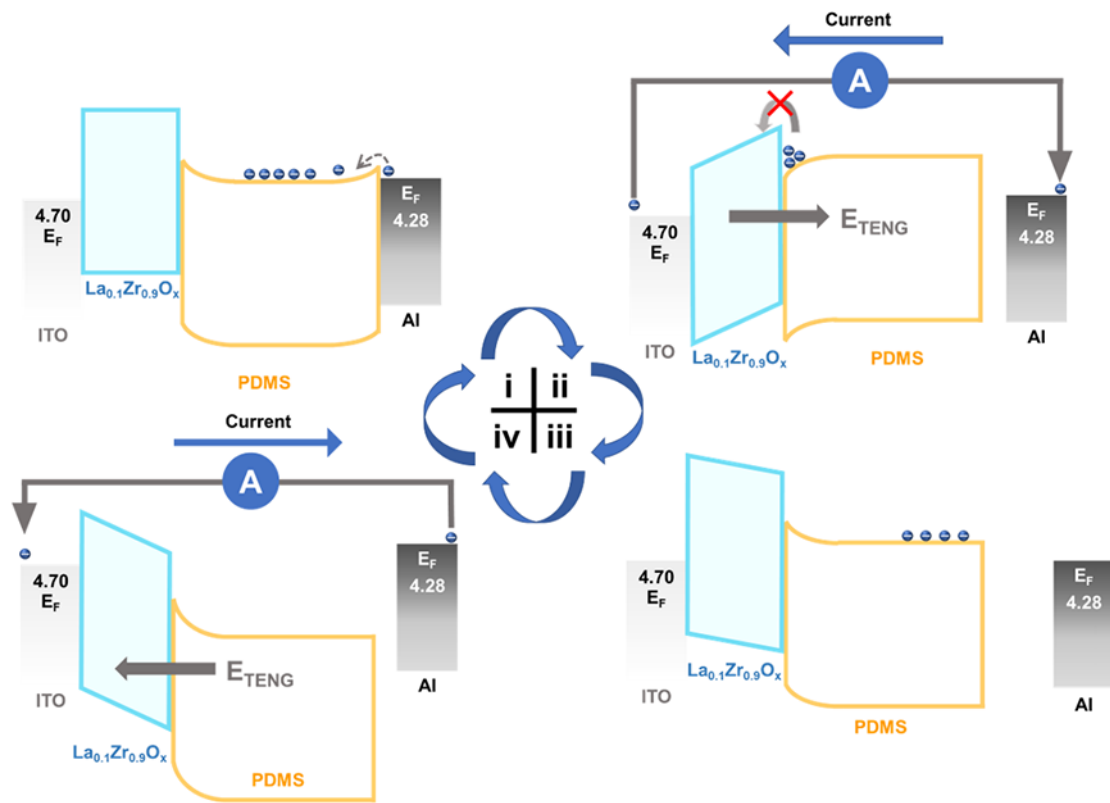


Fig. S9 The band alignment of $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ based TENG during different states of a single contact separation cycle.

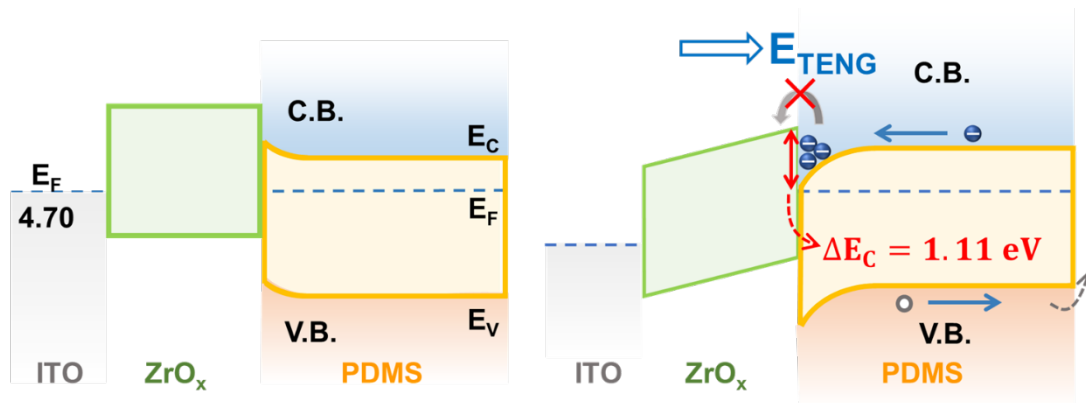


Fig. S10 Energy band diagram of ZrO_x based TENG before and (h) after triboelectrification.

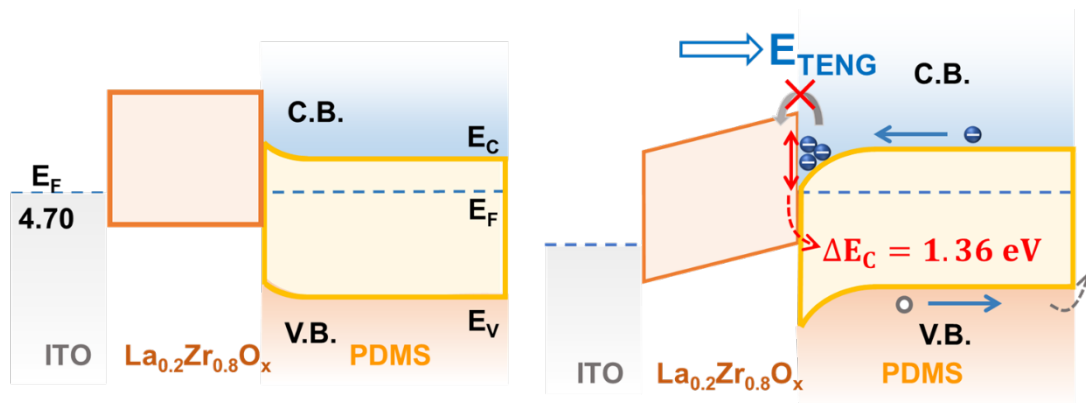


Fig. S11 Energy band diagram of $\text{La}_{0.2}\text{Zr}_{0.8}\text{O}_x$ based TENG before and (h) after triboelectrification.

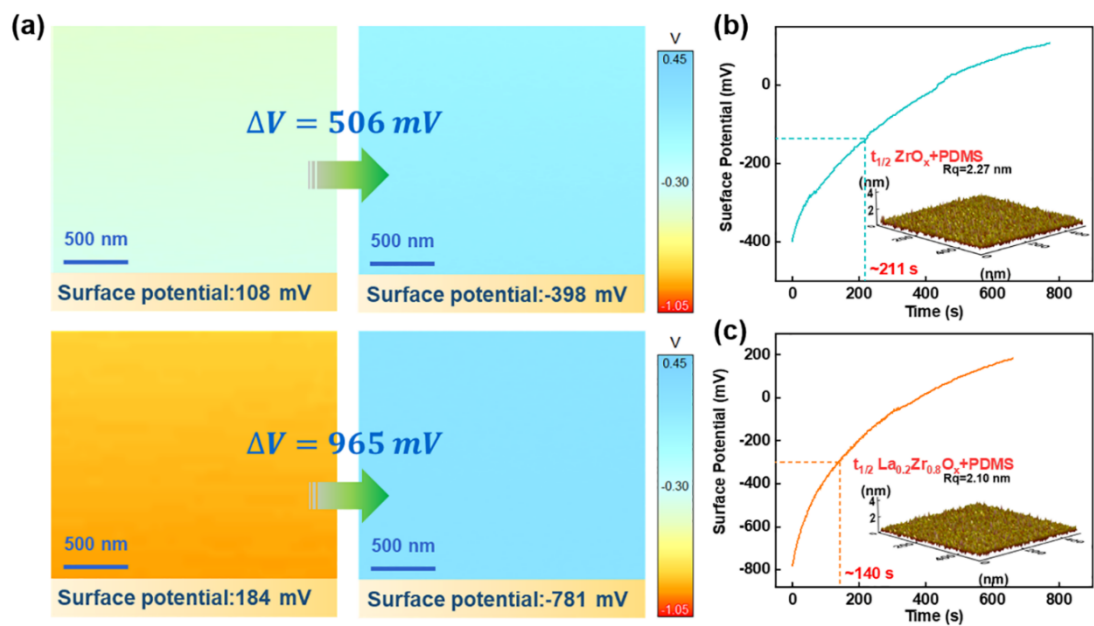


Fig. S12 Contact potential difference and surface charge decay pattern of ZrO_x H-TENG and $\text{La}_{0.2}\text{Zr}_{0.8}\text{O}_x$ H-TENG.

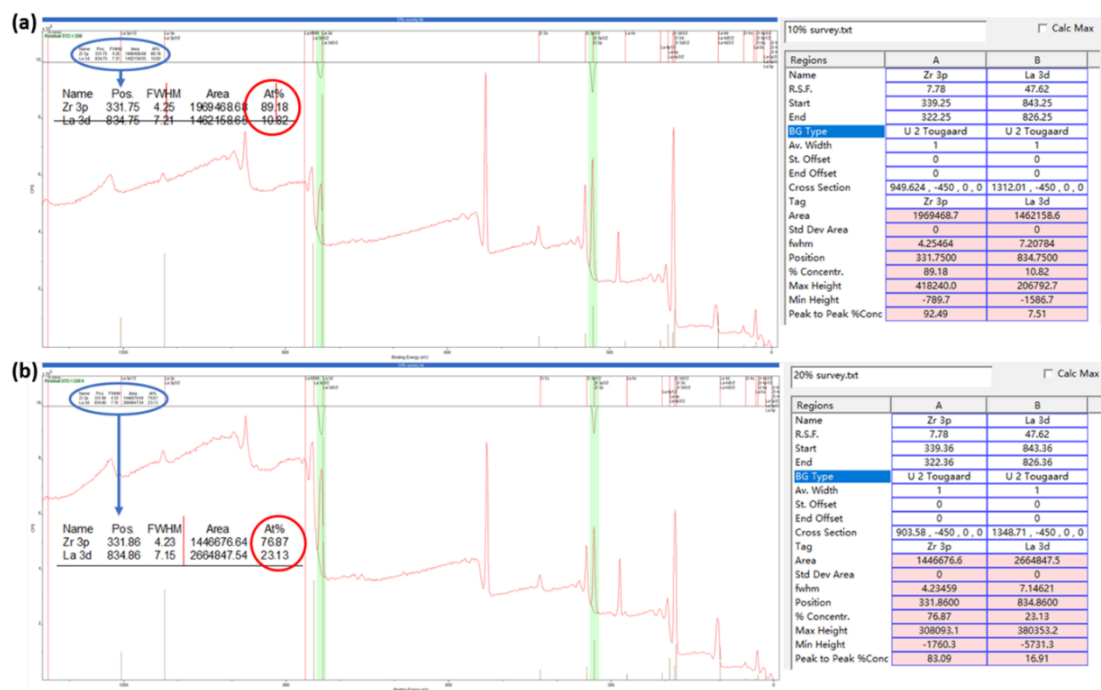


Fig. S13 CasaXPS software utilized to calculate the atomic ratio according to XPS survey spectra.

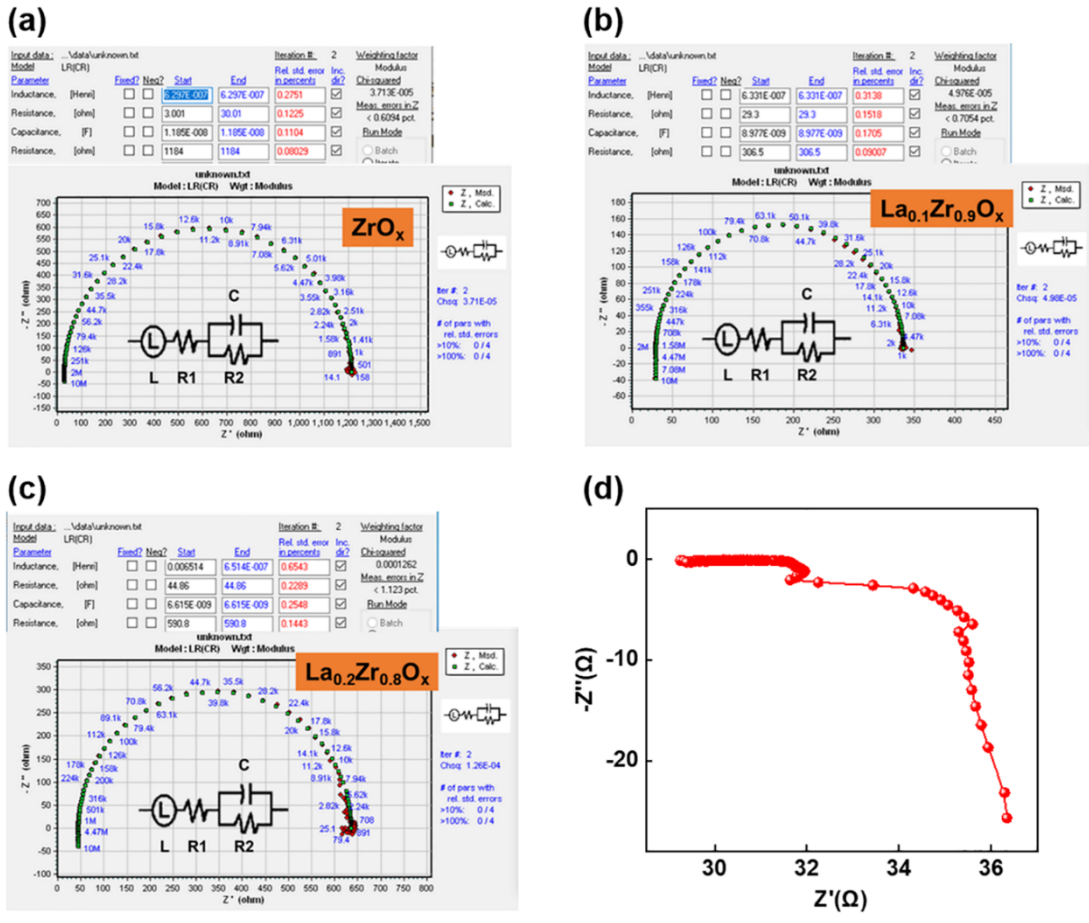


Fig. S14 The EIS measurement results and simulated parameters of (a) ZrO_x, (b) La_{0.1}Zr_{0.9}O_x, (c) La_{0.2}Zr_{0.8}O_x and (d) ITO thin films.

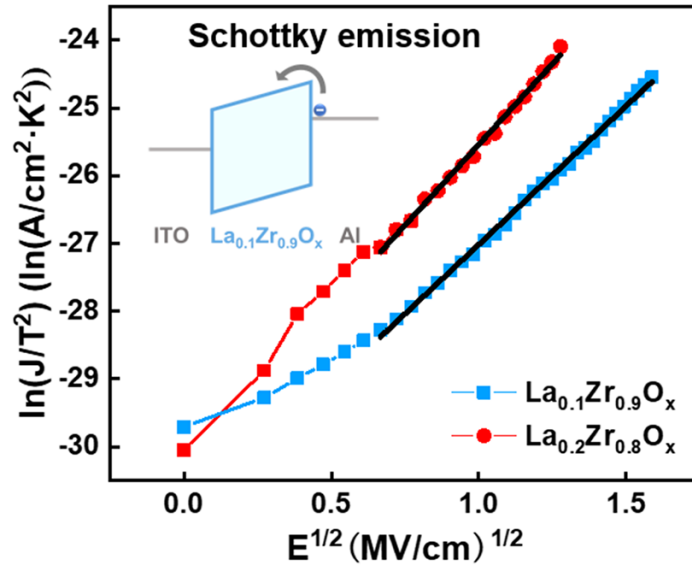


Fig. S15 Schottky emission plot of LaZrO films with La concentration varying from 10 to 20%.

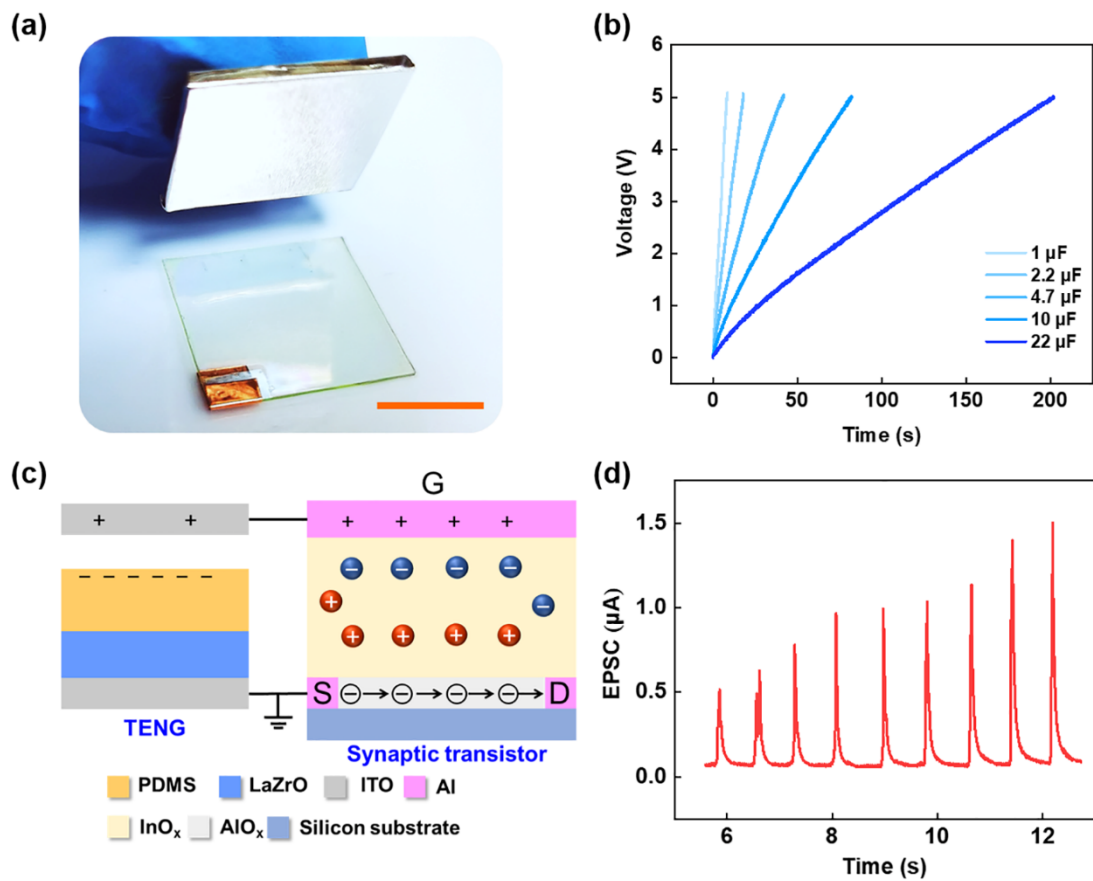


Fig. S16 Device of the $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ based H-TENG and two practical applications. (a) Optical photograph of the $\text{La}_{0.1}\text{Zr}_{0.9}\text{O}_x$ based H-TENG, (b) application of charging different capacitors, (c) cross-section view and (d) application of contact electrification activated biological synaptic behavior.